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Translation of Claim 1:

An improved method for fabricating a printed circuit board, comprising:

placing a substrate in a 10% solution of an acidic detergent to degrease for 2 minutes and then washing the substrate with water so as to clean the surfaces of the substrate;

placing the substrate into a mixed solution of 100 g/L sodium persulfate in 2 - 5% sulfuric acid to thereby subject the same to a micro-etching process for 0.5 - 2 minutes and subsequently cleaning the substrate with water so as to improve adhesive capability of the surfaces of the substrate;

presoaking the substrate in 3 - 5% (preferably 5%) sulfuric acid for 1 minute, and then transferring the substrate into a dilute solution of 120 - 200 g/L (preferably 150 g/L) sulfuric acid and 40 - 120 g/L (preferably 75 g/L) copper sulfate, in which chlorine is mixed at a concentration of 30 - 100 ppm (preferably 60 ppm) and a brightening agent is added at a concentration of 2 - 10 ml/L, to thereby carry out a copper plating process for 45 minutes, the substrate being washed with water at the end of the copper plating process; and

presoaking the substrate in 3 - 5% sulfuric acid for 1 minute, and then transferring the substrate into a mixed solution of 100 - 250 g/L (preferably 140 g/L) sulfuric

acid, 10 - 80 g/L (preferably 40 g/L) tin sulfate, 10 - 100 g/L (preferably 40 g/L) of additives and 2 - 500 ppm (preferably 350 ppm) of alloy ions (thallium, indium, antimony, bismuth and tin), so as to carry out a tin alloy plating process, whereby the outermost layer of a substrate surface is deposited with an etching resist layer made of an alloy of thallium, indium, antimony, bismuth and tin.